

AMENDMENTS

In the Claims:

This listing of claims replaces all prior versions, and listings, of claims in this application.

1. (Currently Amended) A ~~heat-resistant resin laminate film~~ having a metal layer, comprising:

a heat-resistant insulating film ~~[[, and]]~~ having a coefficient of linear expansion of 5 to 25 ppm/°C and a thickness of 5 to 75 μm ;

at least one heat-resistant resin layer laminated on at least one surface of said heat-resistant insulating film~~[[,]]~~ ; and

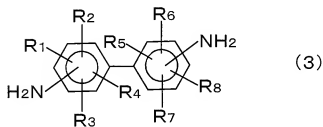
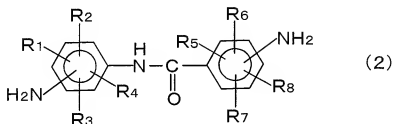
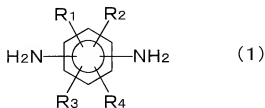
at least one metal layer formed on said at least one heat-resistant resin layer, wherein said heat-resistant resin layer comprises at least two sublayers, said two sublayers including a heat resistant resin sublayer A having a coefficient of linear expansion kA (ppm/°C) within the range of $k-10 < k_A < k+20$, wherein k represents the coefficient of linear expansion of said heat-resistant insulating film, and a heat-resistant resin sublayer B having a glass transition temperature lower than that of said heat-resistant resin sublayer A, said heat-resistant resin sublayer A being laminated in contact with said metal layer, and said heat-resistant resin sublayer B being laminated in contact with said heat-resistant insulating film.

2. (Canceled)

3. (Currently Amended) The ~~heat-resistant resin laminate film~~ having a metal layer according to claim 1, wherein said ~~heat-resistant insulating film~~ has a coefficient of linear expansion of 5 to 25 ppm/°C, and said heat-resistant resin layer sublayer A having the coefficient of linear expansion kA (ppm/°C) ~~within the range of $k-10 < k_A < k+20$~~ has a coefficient of linear expansion of 5 to 30 ppm/°C.

4. (Currently Amended) The ~~heat-resistant resin laminate film~~ having a metal layer according to claim 1, wherein the resin constituting said heat-resistant resin layer sublayer A having the coefficient of linear expansion kA (ppm/°C) within the range of $k-10 < k_A < k+20$ is a polyimide resin comprising as a diamine component at least one aromatic diamine represented

by any of the Formulae (1) to (3) in an amount of not less than 40 mol% based on the total diamine component:



wherein R^1 to R^8 are the same or different and are selected from the group consisting of hydrogen, C_1 - C_{30} alkyl, C_1 - C_{30} alkoxy, halogen, hydroxy, carboxyl, sulfonic, nitro and cyano.

5. (Currently Amended) The ~~heat-resistant resin~~ laminate film having a metal layer according to claim 4, wherein said diamine component of said polyimide resin comprises at least one selected from the group consisting of *p*-phenylenediamine, 4,4'-diaminobenzanilide and 2,2'-dimethylbenzidine, in an amount of not less than 40 mol% based on the total diamine component.

6. (Currently Amended) The ~~heat-resistant resin~~ laminate film having a metal layer according to claim 4, wherein a tetracarboxylic acid component of said polyimide resin comprises pyromellitic dianhydride ~~and/or~~, biphenyltetracarboxylic dianhydride, or a combined

total of both, in an amount of not less than 40 mol% based on the total tetracarboxylic acid component.

7-8. (Canceled)

9. (Currently Amended) The laminate film having a metal layer(s) layer according to claim [[8]] 1, wherein said heat-resistant resin layer sublayer A has a glass transition temperature of 250°C to 400°C.

10. (Currently Amended) The laminate film having a metal layer according to claim [[8]] 1, wherein said heat-resistant resin layer sublayer A has a thickness of not less than twice that of said heat-resistant resin layer sublayer B.

11. (Currently Amended) The laminate film having a metal layer according to claim [[8]] 1, wherein said heat-resistant resin layer sublayer B consists essentially of polyimide resin.

12. (Currently Amended) The laminate film having a metal layer(s) layer according to claim [[11]] 1, wherein said heat-resistant resin layer sublayer B has a glass transition temperature of 120°C to 280°C.

13. (Currently Amended) The laminate film having a metal layer according to claim [[8]] 1, wherein said heat-resistant resin layer sublayer B consists essentially of a thermosetting resin containing an epoxy compound.

14. (Currently Amended) The laminate film having a metal layer according to claim 13, wherein said heat-resistant resin layer sublayer B has a glass transition temperature of 50°C to 250°C.

15. (Currently Amended) A semiconductor device comprising said laminate film having a metal layer according to claim [[6]] 1.

16. (Currently Amended) A process of producing a laminate film having a metal layer comprising a heat-resistant insulating film and a metal layer laminated on at least one surface of said heat-resistant insulating film through a heat-resistant resin layer(s) layer, said process comprising:

laminating at least one heat-resistant resin layer including a heat-resistant resin layer having a coefficient of linear expansion k_A (ppm/ $^{\circ}$ C) within the range of $k-10 < k_A < k+20$, wherein k represents the coefficient of linear expansion of said heat-resistant insulating film, on said metal layer;

laminating the resulting metal layer/heat-resistant resin layer laminate and said heat-resistant insulating film; and

heat pressing the resulting laminate.

17. (Canceled)